Rogers High Frequency Circuit Materials

	Property	RT/duroid® 5880	RT/duroid® 5870	ULTRALAM®	RT/duroid®	RT/duroid® 6006	RT/duroid® 6010LM	TMM® 3	TMM® 4	TMM® 6	TMM® 10	TMM® 10j
Com	position	PTFE Glass Fiber	PTFE Glass Fiber	PTFE Woven Glass	PTFE Ceramic	PTFE Ceramic	PTFE Ceramic	Hydro- Carbon Ceramic	Hydro- Carbon Ceramic	Hydro- Carbon Ceramic	Hydro- Carbon Ceramic	Hydro- Carbon Ceramic
ε _r ⁽¹⁾ Tole	rance	2.20 ±0.020	2.33 ±0.020	2.40-2.60 ±0.040	2.94 ±0.040	6.15 ±0.150	10.2 ±0.250	3.27 ±0.032	4.50 ±0.045	6.00 ±0.080	9.20 ±0.230	9.80 ±0.245
Tan	δ ⁽¹⁾	0.0009	0.0012	0.0019	0.0012	0.0019	0.0023	0.0020	0.0020	0.0023	0.0023	0.0020
coefi -50° ppm	Thermal coeff. of £ ⁽²⁾ -50° to150°C ppm/ °C		-115	-100	+12	-410	-425	⁽⁴⁾ +39	_	⁽⁴⁾ -10	⁽⁴⁾ -38	⁽⁴⁾ -43
resis Mohr	Volume resistivity Mohm•cm (Typical)		2x10 ⁷	2x10 ⁷	106	2x10 ⁷	5x10⁵	3x10 ⁹	6x10 ⁸	1x10 ⁸	2x10 ⁷	_
Surfa resis Moh (Typi	stivity m	3x10 ⁸	2x10 ⁸	4x10 ⁷	10 ⁷	7x10 ⁷	5x10 ⁶	>9x10 ⁹	1x10 ⁹	1x10 ⁹	4x10 ⁷	_
lus ⁽³⁾	X - kpsi (MPa)	156 (1,076)	189 (1,340)	1700 (11,730)	120 (828)	74 (511)	135 (932)	1916 (13,210)	2000* (13,790)	2200 (15,168)	2400 (16,547)	
s Modulus ⁽³⁾	Y - kpsi (MPa)	125 (863)	185 (1,277)	1300 (8,970)	120 (828)	91 (628)	81 (559)	1916 (13,210)	2000* (13,790)	2200* (15,168)	2400 (16,547)	-
, nud,	Z - kpsi (MPa)	136 (938)	120 (828)	_	360* (2,482)	155 (1,070)	311 (2,146)	742 (5,116)	752 (5,185)	736 (5,075)	575 (3,964)	-
abso	sture ⁽⁴⁾ orption 23 % ical)	0.015	0.015	0.03	0.1	0.05	0.05	⁽⁴⁾ 0.04	⁽⁴⁾ 0.010	⁽⁴⁾ 0.06	⁽⁴⁾ 0.09	⁽⁴⁾ 0.16
cond W/m (Typi	ical)	0.20	0.22	0.24	0.60	0.49	0.78	0.70	0.70	0.72	0.76	0.76
Coefficient of Thermal Expansion ppm/°C ⁽⁶⁾	(typ) X	31	22	15	16	47	24	16	14	16	16	16*
ient of	ο100°C γ	48	28	15	16	34	24	16	14	16	16	16*
Coeffic Expar	° Z	237	173	200	24	117	24	20	20	20	20	20*
Dens gm/c (typic	cm ³	2.2	2.2	2.2	2.1	2.7	3.1	1.78	2.07	2.37	2.77	2.77

Rogers High Frequency Circuit Materials

Property		RO30037m	R032037m	RO3006 TM	RO30107W	R03210TM	R04003®	R04350®
Composition		PTFE Ceramic	PTFE Ceramic Reinforced Woven Glass	PTFE Ceramic	PTFE Ceramic	PTFE Ceramic Reinforced Woven Glass	Hydrocarbon Ceramic Woven Glass	Hydrocarbon Ceramic Woven Glass
$\epsilon_{_{r}}^{^{(1)}}$ Tolerance		3.00 - 0.04	3.02 - 0.04	6.15- 0.15	10.2 – 0.30	10.2- 0.5	3.38- 0.05	3.48- 0.05
Tan δ ⁽¹⁾		0.0013	0.0016	0.0025	0.0035	0.003	0.0027	0.004
Thermal coefficient of $\epsilon_{\rm r}^{~(2)}$ ppm/ C (-50 to 150 C)		13	13	-160	-280	13	+40	+50
Volume resistivity (Mohm cm) (typical)		106	107	10³	10³	104	1.7 x 10 ¹⁰	1.2 x10 ¹⁰
Surface resistivity (Mohm)		10 ⁷	10 ⁷	10³	10³	104	4.2 x 10 ⁹	5.7 x 10 ⁹
Youngs modulus (3)	X-kpsi (MPa)	300 (2068)		300 (2068)	300 (2068)		3700 (25,510)	
Toungs modulus	Y-kpsi (MPa)	300 (2068)		300 (2068)	300 (2068)		3900 (26,889)	1664 (11,473)
Moisture absorption ⁽⁴⁾ D24/23 (%) (typical)		<0.1	<0.1	<0.1	<0.1	<0.1	0.06	0.06
Copper peel strength lbs/in (N/mm)		17.6 (3.1)	10 (1.7)	12.2 (2.1)	13.4 (2.4)	10 (1.7)	6.4 (1.1)	5.3 (0.9)
Thermal conductivity (5) (W/m/ K)		0.50	0.50	0.61	0.66	0.81	0.64	0.62
Coefficient of thermal expa 0 to 100 C (ppm/ C)	nsion ⁽⁶⁾ X Y Z	17 17 24	13 13 58	17 17 24	17 17 24	13 13 34	11 14 46	14 16 50
Density gm/cm³ (typical)		2.1	2.1	2.6	3.0	3.0	1.8	1.9
Flammability rating, UL 94V	' -0	Yes	Yes	Yes	Yes	Yes	No	Yes

*estimated

Young's modulus (elastic modulus), steepest region of the stress/strain curve is in tension for X and Y axes by ASTM D 638; in compression for Z axis by ASTM D 695 on 12.7 x 12.7 x 25.4 mm stacked speciman. Data are typical only. Testing conditions: 24 hours @ 23°C, specimans etched free of copper. 3) 4)

RT/duroid, DUROID, TMM, ULTRALAM, RO3003, RO3006, RO3010, RO4003, and RO4350 are licensed trademarks of Rogers Corporation for their microwave laminates. The information and guidelines contained in this document are intended to assist you in designing with RT/duroid, TMM, ULTRALAM, RO3003, RO3006, RO3010, RO4003 and RO4350 laminates. They are not intended to and do not create any warranties, express or implied including any warranty of merchantability or fitness for a particular application. Results may vary as conditions and equipment vary. The user should determine the suitability of Rogers materials for each specific application.

Measured by IPC-TM-650 method 2.5.5.5 at ~10 GHz, 23°C. RT/duroid 6010 materials were based on testing a 0.025° thick sheet clad with 1 oz. electrodeposited copper. e, values and tolerances reported by IPC-TM-650 method 2.5.5.5 are the basis for quality acceptance, but for some products these values may be incorrect for design engineering applications, especially those in microstrip. We recommend that prototype boards of a new design be verified for electrical

Measured by IPC-TM-650 method 2.5.5.5 at ~10 GHz modified. Data are typical only.

Tested by ASTM D3386-94. Values are average over temperature range but not necessarily linear. However, for RT/duriod 6002 and TMM grades the response is essentially linear.

Cladding Metals

	Copper Foil	Treated Side	e Roughne	Tensile Strength kpsi (MPa)	Elongation %	Volume Resistivity Microhm•cm	Stress Crack Resistance	Thickness mil	Peel Strength RT/duroid®5000 Ibs/in (KN/m)
1/4 oz ED	(9µm)	70 (1.8)	15 (0.4)	_	_	1.87	Fair	0.4	11 (1.93)
1/2 oz ED	(17.5µm)	75 (1.9)	15 (0.4)	33.0 (228)	20.0	1.82	Fair	0.7	12 (2.10)
1 oz ED	(35µm)	95 (2.4)	15 (0.4)	30.0 (207)	28.0	1.78	Fair	1.4	16 (2.80)
2 oz ED	(70µm)	115 (2.9)	15 (0.4)	32.0 (221)	42.0	1.78	Fair	2.8	18 (3.15)
1/2 oz Rolled	(17.5µm)	55 (1.4)	12 (0.3)	20.0 (138)	8.0	1.78	Excellent	0.7	9 (1.58)
1 oz Rolled	(35µm)	55 (1.4)	12 (0.3)	22.0 (152)	13.0	1.74	Excellent	1.4	10 (1.75)
2 oz Rolled	(70µm)	55 (1.4)	12 (0.3)	28.0 (193)	27.0	1.74	Excellent	2.8	11 (1.93)

Plates	Alloy	Surface Roughness µin (µm)	Machinability	Tensile Strength kpsi (MPa)	Specific Gravity	Thermal Conductivity W/m/°K	Coefficient of Thermal Expansion	Resisitivity microhm cm	
Aluminum	6061	70 (1.8)	Poor	20 (138)	2.7	180	24	5	
Brass	70/30 cartridge	70 (1.8)	Good	45 (311)	8.5	120	20	6	
Copper	110	70 (1.8)	Fair to Poor	35 (242)	8.9	390	17	2	

Ordering Information

Rogers circuit laminates can be purchased by contacting your customer service representative at (602) 961-1382 or one of our overseas offices listed below.

To ensure you receive the right material for your application, please include order information for each of the categories listed below. For more detailed product information, refer to the charts in this product selector guide.

GRADE:

TMM 3,4,6,10, and 10i Ceramic Thermoset Polymer Composite Circuit Board Materials, RT/duroid 5870 and 5880 Glass Microfiber Reinforced Polytetrafluoroethylene Composite Materials, ULTRALAM 2000 Woven Glass Reinforced Polytetrafluoroethylene Material, RT/duroid 6002 Polytetrafluoroethylene Composite Material, RT/duroid 6006, 6010 and 6010LM Ceramic Polytetrafluoroethylene Composite Materials. RO3003, RO3203, RO3006, RO3010, RO3210, RO4003 and RO4350 High Frequency Circuit Materials.

THICKNESS AND TOLERANCE:

Dielectric is the thickness without copper. Refer to the price list(s) for standard thicknesses and tolerances. Custom thicknesses and tolerances are available on RT/duroid laminates and TMM laminates upon request.

TYPE OF FOIL AND CLADDING:

RT/duroid, laminates - ¼, ½, 1, and 2 ounce electrodeposited copper,

½, 1, and 2 ounce rolled copper or unclad (unclad is not available in dielectric thicknesses less than 0.010).

ULTRALAM, - ½, 1, and 2 ounce electrodeposited copper,

½, 1, and 2 ounce rolled copper.

TMM laminates - ¼, ½, 1, and 2 ounce electrodeposited copper

foil two sides. TMM may also be supplied unclad.

*RO3003, *RO3203, *RO3006,

*RO3210, *RO3010 laminates - ½ and 1 ounce electrodeposited copper two sides. *RO4003 laminates - ½ and 1 ounce electrodeposited copper two sides.

*RO4003 laminates - ½ and 1 ounce electrodeposited copper two sides. *RO4350 laminates - ½ and 1 ounce electrodeposited copper two sides.

Thick aluminum, copper and brass claddings are also available in a range of thicknesses and thickness tolerances. Other thick metal backings are available upon request.

*Thick metal backing is not available on RO3000 series and RO4000 series laminates.

PANEL SIZE:

See price list for standard panel sizes. Custom panel sizes are available upon request.

SPECIFICATION REQUIREMENTS:

Standard specifications are Rogers material specification. Certificates of conformance are available.

All other specification requirements must be identified at the time the order is placed. If special testing or data generation is required, additional costs may be incurred.

ROGERS

SINCE 1832

Rogers Corporation Microwave Materials Division 100 S. Roosevelt Avenue Chandler, AZ 85226 U.S.A.

Tel: 602 961-1382 FAX: 602 961-4533 Toll Free: 877-643-7701

Website: http://www.rogers-corp.com/mwu/

ISO 9002 CERTIFIED

In Japan:

Rogers Japan Inc., Tokyo 116 Japan Tel: 03-3807-6430 FAX: 03-3807-6319

In Hong Kong:

Rogers Southeast Asia, Sheung Wan, Hong Kong Tel: 852-2549-7806 FAX: 852-2549-8615

In Europe:

Rogers N.V., Gent, Belgium

Tel: 32-9-2353611 FAX: 32-9-2353658

In Taiwan:

Rogers Taiwan Inc, Taipei, Taiwan R.O.C. Tel: 886-2-86609056, FAX: 886-2-86609057